IEEE THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC. CPMT IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY ORANGE COUNTY CHAPTER

IEEE Components, Packaging and Manufacturing Technology Society

Orange County Chapter

Tuesday, August 19, 2014 Tutorial

Advance Package Failure Analysis Methods

Winfield Scott

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OVERVIEW:

This tutorial will provide an overview of the Failure Analysis process as it relates to electronic packaging. Attendees will learn about:

- The FA methodology and flow
- The importance of a failure's background history
- Destructive and non-destructive analytical steps including decapsulation and CSAM
- Electrical and physical FA; e.g. curve tracing, cross-section, and SEM
- Advanced techniques: TDR, SQUID and 3D X-ray

WHO SHOULD ATTEND:

IC Packaging Design / Development / Reliability engineers, Chip Design Engineers and Managers who would like to learn about Failure Analysis techniques to understand Semiconductor Chip / Package Failure Modes

ABOUT THE INSTRUCTOR:

Winfield Scott is the Director of Technology at Evans Analytical Group and has the responsibility to ensure EAG has the tools and techniques to keep up with the advances in semiconductors and electronic packaging. He has been using FA to help solve problems for over 40 years. In addition to EAG, he has worked for Motorola, Western Digital, and Sperry Flight Systems.

Date: **Tuesday, August 19th, 2014**

Location: **Broadcom Corporation. 5300 California Ave, Irvine, CA 92617**
Bldg. 2 – 1st Floor Conference Room – Salt Creek

Time: **5:00pm: Registration, 5:30pm – 7:30pm: Short Course, 7:30pm - Dinner**

Registration Fee: **IEEE members - $10;**
Non-members of IEEE - $20;
Student IEEE members - FREE;
Student Non-IEEE Members - $5 (includes Dinner & Training material)

To attend, pre-register at http://tinyurl.com/kamdvvb, as the number of seats will be limited.

For more information, please contact Sam Karikalan at samk@broadcom.com or Bob Warren at Robert.Warren@conexant.com.